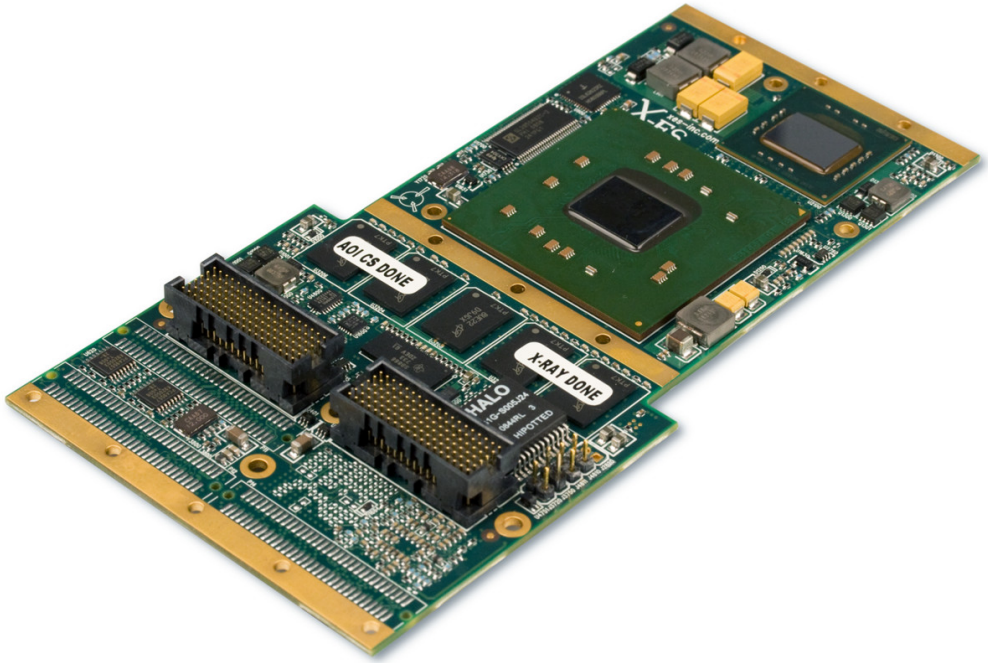
XPedite7101

End Of Life

Intel® Core™2 Duo Processor-Based XMC/PMC Module

Please see XPedite7501

- Intel® Core™2 Duo processor at up to 1.8 GHz
- XMC/PMC module
- Conduction or air cooling
- Up to 2 GB of DDR2-400 ECC SDRAM
- 2 MB firmware hub flash (or 1 MB with redundancy)
- 4 GB of NAND flash
- x4 PCI Express XMC interface
- 32-bit, 33/66 MHz PCI PMC interface
- Gigabit Ethernet port with integrated magnetics
- Two USB 2.0 high-speed ports
- Four SATA 1.5 Gb/s ports
- Two RS-232 ports or one RS-422/485 port
- Linux BSP
- Wind River VxWorks BSP
- QNX Neutrino BSP
- Green Hills INTEGRITY BSP
- Microsoft Windows drivers



XPedite7101

The XPedite7101 is a high-performance, low-power XMC/PMC module based on the Intel® Core™2 Duo processor. With a x4 PCI Express or 32-bit, 33/66-MHz PCI interconnect and a Gigabit Ethernet port, the XPedite7101 is ideal for high-bandwidth data-processing applications.

The XPedite7101 accommodates up to 2 GB of DDR2-400 ECC SDRAM to support memory-intensive applications, and hosts numerous I/O ports including Gigabit Ethernet, USB 2.0, SATA 1.5 Gb/s, and RS-232 or RS-422/485 serial.

Linux 2.6, Wind River VxWorks, QNX Neutrino, and Green Hills INTEGRITY Board Support Packages (BSPs), as well as Microsoft Windows drivers, are available for the XPedite7101.

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...Always Fast

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Processor

- Intel® Core™2 Duo at up to 1.8 GHz
- 200 MHz (800 MT/s) FSB
- Up to 6 MB of L2 cache

Memory

- Up to 2 GB of DDR2-400 ECC SDRAM
- 2 MB firmware hub flash (or 1 MB with redundancy)
- 4 GB of NAND flash

PMC Interface

- 33/66 MHz PCI
- 32-bit Interface

P14 or P16 Mezzanine Interface

- Two USB 2.0 ports
- Four SATA 1.5 Gb/s ports
- Two RS-232 ports or one RS-422/485 port
- One 10/100/1000BASE-T Ethernet port
- Four GPIO Signals

P15 XMC Interface

- x4 PCI Express

Software

- Linux BSP
- Wind River VxWorks BSP
- QNX Neutrino BSP
- Green Hills INTEGRITY BSP
- Microsoft Windows drivers

Physical Characteristics

- XMC/PMC form factor
- Dimensions: 149 mm x 74 mm, 10 mm stacking height

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1, 3, 5
- Conformal coating available as an ordering option

Power Requirements

- Power will vary based on configuration and usage. Please consult factory.

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C ambient
Vibration	0.002 g²/Hz, 5 to 2000 Hz	0.04 g²/Hz (maximum), 5 to 2000 Hz	0.1 g²/Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing